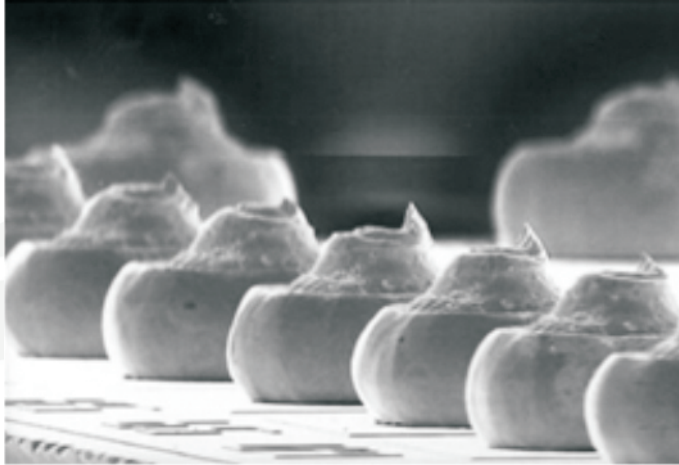


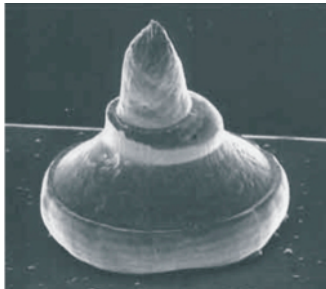
POST PROCESS ON WAFER OR CHIP



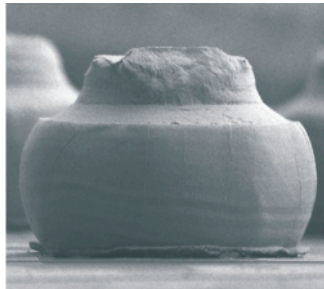
DIAMETER : 60 - 120 μ m
HEIGHT : 45 - 60 μ m
CADENCE : UP TO 35 BUMPS/SEC

BUMPING ON :
- WAFER UP TO 12"
- BLUE FOIL
- SAWN WAFER
- SINGLE CHIP

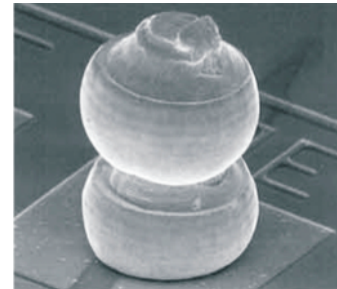
STANDARD BUMP



ACCU BUMP

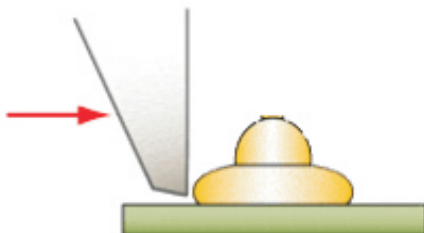


STACKED ACCU BUMP



HYBRID SA IS ABLE TO PLACE GOLD STUD BUMPS ON CHIPS. BUMP SHAPE IS DEFINED IN COLLABORATION WITH THE CLIENT IN ORDER TO MATCH CHIP ASSEMBLY SPECIFICATIONS.

SHEAR TEST



APPLICATION OF THE FORCE UNTIL BUMP FAILURE.